

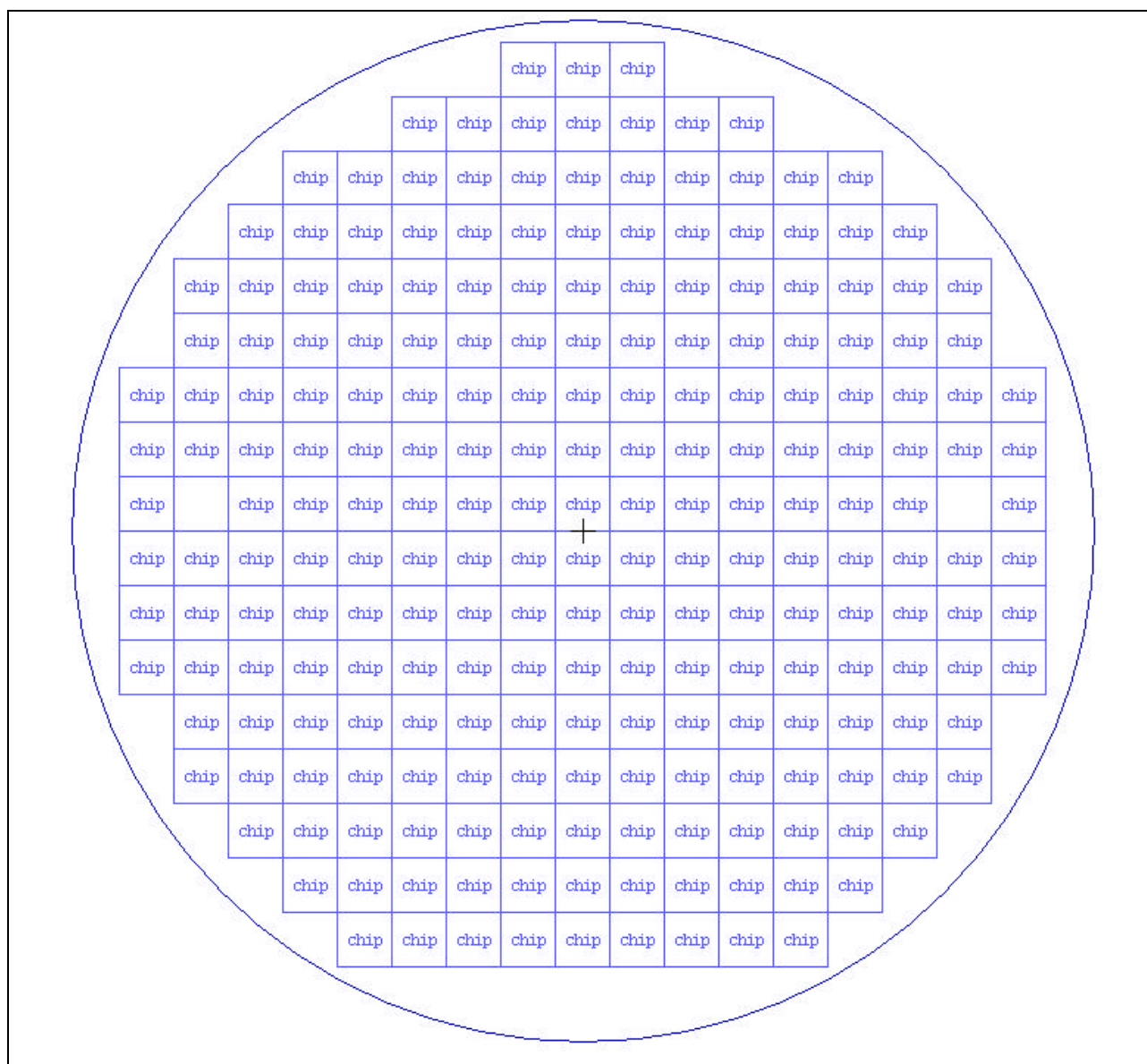
Flip Chip Testwafer NOK1-1

Test Chips Specifications

1. General data

chip no	chip size / mm	pitch / μm	pad configuration	I/O's	chips per wafer
1	8,0 x 8,0	160	staggered	352	227

2. Wafer mapping



3.1 Chip documentation NOK 1-1

Chip 1	Chip size : 8 x 8 mm		
pitch	160 μm	Distance to Neural Point / DNP	5.657 mm
pad size	80 μm	symmetry	X, Y
passivation opening	70 μm	saw trace width	120 μm
bump size*	80 μm	dist. pad center to chip edge**	200 μm
pad configuration	staggered	daisy chain structures	4 x 44
pad geometry	octagonal	four point Kelvin structures	-
number of pads	352 I/O's	alignment marks / FC	no
pad material	1 μm AlSi	alignment marks / lithography	yes

*size of Ni/Au UBM: 5 μm

**excluding saw trace

